

# NB6L72M

## 2.5V / 3.3V Differential 2 X 2 Crosspoint Switch with CML Outputs

### Multi- Level Inputs w/ Internal Termination

#### Description

The NB6L72M is a clock or data high-bandwidth fully differential 2 x 2 Crosspoint Switch with internal source termination and CML output structure, optimized for low skew and minimal jitter. The differential inputs incorporate internal 50  $\Omega$  termination resistors and will accept LVPECL, CML, LVDS, LVCMOS, or LVTTTL logic levels. The SELECT inputs are single-ended and can be driven with LVCMOS/LVTTTL.

The 16 mA differential CML outputs provide matching internal 50  $\Omega$  terminations and 400 mV output swings when externally terminated with a 50  $\Omega$  resistor to  $V_{CC}$ .

The device is offered in a small 3 mm x 3 mm 16-pin QFN package.

The NB6L72M is a member of the ECLinPS MAX™ family of high performance clock and data management products.

#### Features

- Input Clock Frequency > 3.0 GHz
- Input Data Rate > 3 Gb/s
- 360 ps Typical Propagation Delay
- 65 ps Typical Rise and Fall Times
- Differential CML Outputs, 380 mV peak-to-peak, typical
- Operating Range:  $V_{CC} = 2.375$  V to 3.63 V with GND = 0 V
- Internal Input and Output Termination Resistors, 50  $\Omega$
- Functionally Compatible with Existing 2.5 V / 3.3 V LVEL, LVEP, EP, and SG Devices
- -40 °C to +85°C Ambient Operating Temperature
- These are Pb-Free Devices



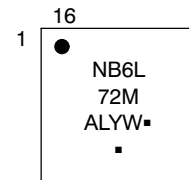
ON Semiconductor®

<http://onsemi.com>

#### MARKING DIAGRAM\*



QFN-16  
MN SUFFIX  
CASE 485G



A = Assembly Location  
L = Wafer Lot  
Y = Year  
W = Work Week  
▪ = Pb-Free Package  
(Note: Microdot may be in either location)

\*For additional marking information, refer to Application Note AND8002/D.

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 9 of this data sheet.

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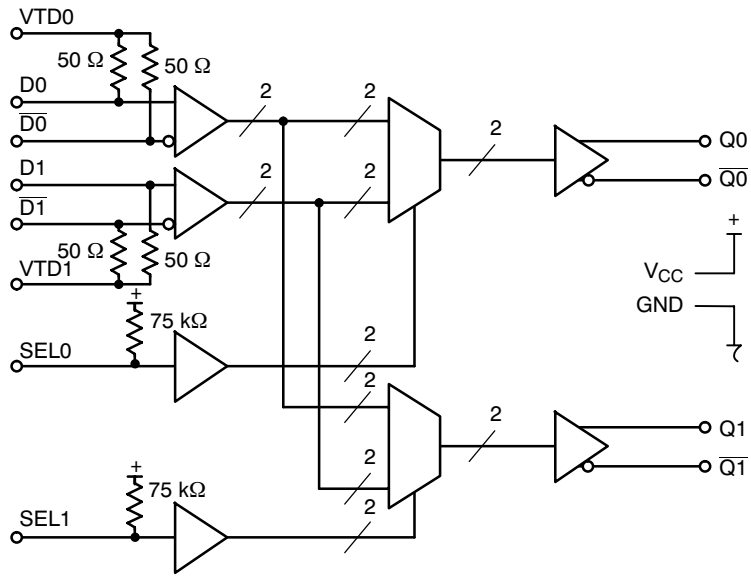


Figure 1. Logic/Block Diagram

# NB6L72M

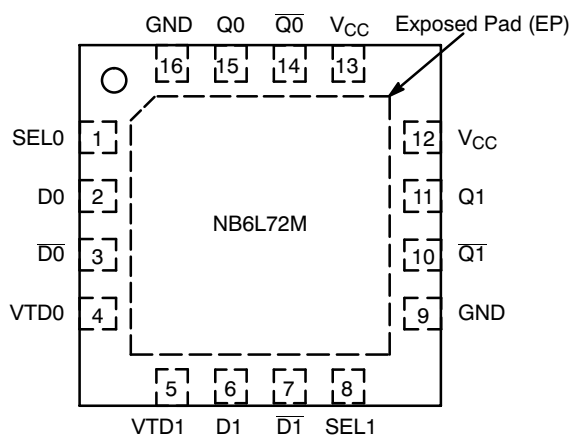


Figure 2. Pin Configuration (Top View)

Table 1. INPUT/OUTPUT SELECT TRUTH TABLE

SEL0*	SEL1*	Q0	Q1
L	L	D0	D0
H	L	D1	D0
L	H	D0	D1
H	H	D1	D1

\*Defaults HIGH when left open

Table 2. PIN DESCRIPTION

Pin	Name	I/O	Description
1	SEL0	LVTTTL, LVCMOS Input	Select Logic Input control that selects D0 or D1 to output Q0. See Table 1, Select Input Function Table. Pin defaults HIGH when left open
2	D0	LVPECL, CML, LVDS, LVTTTL, LVCMOS, Input	Noninverted Differential Input. Note 1
3	D0-bar	LVPECL, CML, LVDS, LVTTTL, LVCMOS, Input	Inverted Differential Input. Note 1
4	VTD0	-	Internal 50 Ω Termination Pin. Note 1.
5	VTD1	-	Internal 50 Ω termination pin. Note 1.
6	D1	LVPECL, CML, LVDS, LVTTTL, LVCMOS, Input	Noninverted Differential Input. Note 1.
7	D1-bar	LVPECL, CML, LVDS, LVTTTL, LVCMOS, Input	Inverted Differential Input. Note 1
8	SEL1	LVTTTL, LVCMOS Input	Select Logic Input control that selects D0 or D1 to output Q1. See Table 1, Select Input Function Table. Pin defaults HIGH when left open
9	GND	-	Negative Supply Voltage
10	Q1-bar	CML Output	Inverted Differential Output. Typically Terminated with 50 Ω Resistor to V <sub>CC</sub> .
11	Q1	CML Output	Noninverted Differential Output. Typically Terminated with 50 Ω Resistor to V <sub>CC</sub> .
12	V <sub>CC</sub>	-	Positive Supply Voltage
13	V <sub>CC</sub>	-	Positive Supply Voltage
14	Q0-bar	CML Output	Inverted Differential Reset Input. Typically Terminated with 50 Ω Resistor to V <sub>CC</sub> .
15	Q0	CML Output	Noninverted Differential Reset Input. Typically Terminated with 50 Ω Resistor to V <sub>CC</sub> .
16	GND	-	Negative Supply Voltage
-	EP	-	The Exposed Pad (EP) on the QFN-16 package bottom is thermally connected to the die for improved heat transfer out of package. The exposed pad must be attached to a heat-sinking conduit. The pad is not electrically connected to the die, but is recommended to be electrically and thermally connected to GND on the PC board.

1. In the differential configuration when the input termination pin (VTDn) are connected to a common termination voltage or left open, and if no signal is applied on Dn/Dn-bar input, then the device will be susceptible to self-oscillation.
2. All V<sub>CC</sub> and GND pins must be externally connected to a power supply for proper operation.

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**Table 3. ATTRIBUTES**

Characteristics		Value
Interval Input Pulldown Resistor		75 kΩ
ESD Protection	Human Body Model Machine Model	> 2 kV > 200V
Moisture Sensitivity	16-QFN	Level 1
Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in
Transistor Count		
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test		

For additional information, see Application Note AND8003/D.

**Table 4. MAXIMUM RATINGS**

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V <sub>CC</sub>	Positive Power Supply	GND = 0 V		4.0	V
V <sub>IO</sub>	Positive Input/Output Voltage	GND = 0 V	-0.5 ≤ V <sub>IO</sub> ≤ V <sub>CC</sub> + 0.5	4.5	V
V <sub>INPP</sub>	Differential Input Voltage  D - D̄			V <sub>CC</sub> - GND	V
I <sub>IN</sub>	Input Current Through R <sub>T</sub> (50 Ω Resistor)	Static Surge		45 80	mA mA
T <sub>A</sub>	Operating Temperature Range	QFN-16		-40 to +85	°C
T <sub>stg</sub>	Storage Temperature Range			-65 to +150	°C
θ <sub>JA</sub>	Thermal Resistance (Junction-to-Ambient) (Note 3)	0 lfpm 500 lfpm	QFN-16 QFN-16	42 35	°C/W °C/W
θ <sub>JC</sub>	Thermal Resistance (Junction-to-Case)	(Note 3)	QFN-16	4	°C/W
T <sub>sol</sub>	Wave Solder Pb-Free			265	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

3. JEDEC standard multilayer board - 2S2P (2 signal, 2 power) with 8 filled thermal vias under exposed pad.

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**Table 5. DC CHARACTERISTICS, Multi-Level Inputs**  $V_{CC} = 2.375\text{ V to }3.63\text{ V}$ ,  $GND = 0\text{ V}$ ,  $T_A = -40^\circ\text{C to }+85^\circ\text{C}$

Symbol	Characteristic	Min	Typ	Max	Unit
<b>POWER SUPPLY CURRENT</b>					
$I_{CC}$	Power Supply Current (Inputs and Outputs Open)	60	80	105	mA
<b>CML OUTPUTS</b> (Notes 5 and 6)					
$V_{OH}$	Output HIGH Voltage $V_{CC} = 3.3\text{ V}$ $V_{CC} = 2.5\text{ V}$	$V_{CC} - 40$ 3260 2460	$V_{CC} - 10$ 3290 2490	$V_{CC}$ 3300 2500	mV
$V_{OL}$	Output LOW Voltage $V_{CC} = 3.3\text{ V}$ $V_{CC} = 2.5\text{ V}$	$V_{CC} - 500$ 2800 2000	$V_{CC} - 400$ 2900 2100	$V_{CC} - 300$ 3000 2200	mV
<b>DIFFERENTIAL INPUT DRIVEN SINGLE-ENDED</b> (see Figures 6 and 8)					
$V_{th}$	Input Threshold Reference Voltage Range (Note 7)	1050		$V_{CC} - 150$	mV
$V_{IH}$	Single-Ended Input HIGH Voltage	$V_{th} + 150$		$V_{CC}$	mV
$V_{IL}$	Single-Ended Input LOW Voltage	GND		$V_{th} - 150$	mV
$V_{ISE}$	Single-Ended Input Voltage Amplitude ( $V_{IH} - V_{IL}$ )	300		$V_{CC} - V_{EE}$	mV
<b>DIFFERENTIAL INPUTS DRIVEN DIFFERENTIALLY</b> (see Figures 7 and 9) (Note 8)					
$V_{IHD}$	Differential Input HIGH Voltage	1200		$V_{CC}$	mV
$V_{ILD}$	Differential Input LOW Voltage	GND		$V_{CC} - 150$	mV
$V_{ID}$	Differential Input Voltage Swing ( $D_n, \overline{D_n}$ ) ( $V_{IHD} - V_{ILD}$ ) (Note 15)	150		$V_{CC} - V_{EE}$	mV
$V_{CMR}$	Input Common Mode Range (Differential Configuration) (Note 9)	950		$V_{CC} - 75$	mV
$I_{IH}$	Input HIGH Current $D_n/\overline{D_n}$ , ( $V_{TDn}/\overline{V_{TDn}}$ Open)	-150		+150	$\mu\text{A}$
$I_{IL}$	Input LOW Current $D_n/\overline{D_n}$ , ( $V_{TDn}/\overline{V_{TDn}}$ Open)	-150		+150	$\mu\text{A}$
<b>SINGLE-ENDED LVCMOS/LVTTL CONTROL INPUTS</b>					
$V_{IH}$	Single-Ended Input HIGH Voltage	2000		$V_{CC}$	mV
$V_{IL}$	Single-Ended Input LOW Voltage	GND		800	mV
$I_{IH}$	Input HIGH Current	-150		+150	$\mu\text{A}$
$I_{IL}$	Input LOW Current	-150		+150	$\mu\text{A}$
<b>TERMINATION RESISTORS</b>					
$R_{TIN}$	Internal Input Termination Resistor	40	50	60	$\Omega$
$R_{TOUT}$	Internal Output Termination Resistor	40	50	60	$\Omega$

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- CML outputs loaded with  $50\ \Omega$  to  $V_{CC}$  for proper operation.
- Input and output parameters vary 1:1 with  $V_{CC}$ .
- $V_{th}$ ,  $V_{IH}$ ,  $V_{IL}$ , and  $V_{ISE}$  parameters must be complied with simultaneously.
- $V_{th}$  is applied to the complementary input when operating in single-ended mode.
- $V_{IHD}$ ,  $V_{ILD}$ ,  $V_{ID}$  and  $V_{CMR}$  parameters must be complied with simultaneously.
- $V_{CMR}$  minimum varies 1:1 with GND,  $V_{CMR}$  max varies 1:1 with  $V_{CC}$ . The  $V_{CMR}$  range is referenced to the most positive side of the differential input signal.

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**Table 6. AC CHARACTERISTICS**  $V_{CC} = 2.375\text{ V to }3.63\text{ V}$ ,  $GND = 0\text{ V}$ , or  $V_{CC} = 0\text{ V}$ ,  $GND = -2.375\text{ V to }-3.63\text{ V}$ ,  
 $T_A = -40^\circ\text{C to }+85^\circ\text{C}$ ; (Note 10)

Symbol	Characteristic	Min	Typ	Max	Unit	
$V_{OUTPP}$	Output Voltage Amplitude (@ $V_{INPPmin}$ ) (Note 15) (See Figure 15)	$f_{in} \leq 3\text{ GHz}$	250	380		mV
$f_{DATA}$	Maximum Operating Data Rate	3				Gb/s
$t_{PLH}$ , $t_{PHL}$	Propagation Delay (@0.5GHz)	Dn to Qn SELn to Qn	230	360	480	ps
$t_{SKEW}$	Duty Cycle Skew (Note 11) Within Device Skew Device to Device Skew (Note 12)		6.0	20 25 85		ps
$t_{DC}$	Output Clock Duty Cycle (Reference Duty Cycle = 50%)	$f_{in} \leq 3.0\text{ GHz}$	40	50	60	%
$t_{JITTER}$	RMS Random Clock Jitter (Note 13) Peak-to-Peak Data Dependent Jitter (Note 14)	$f_{in} \leq 3.0\text{ GHz}$ $f_{DATA} = 2.5\text{ Gb/s}$ $f_{DATA} = 3.0\text{ Gb/s}$		0.2 5.0 8.0	0.5 15 25	ps
$V_{INPP}$	Input Voltage Swing/Sensitivity (Differential Configuration) (Note 15)		150		2800	mV
$t_r$ , $t_f$	Output Rise/Fall Times @ 0.5 GHz, (20% - 80%),	Q, $\bar{Q}$		65	120	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

10. Measured by forcing  $V_{INPP}$  (minimum) from a 50% duty cycle clock source. All loading with an external  $R_L = 50\ \Omega$  to  $V_{CC}$ . Input edge rates 40 ps (20% - 80%).

11. Duty cycle skew is measured between differential outputs using the deviations of the sum of  $T_{pw-}$  and  $T_{pw+}$  @ 0.5GHz.

12. Device to device skew is measured between outputs under identical transition @ 0.5 GHz.

13. Additive RMS jitter with 50% duty cycle clock signal.

14. Additive peak-to-peak data dependent jitter with input NRZ data at PRBS23.

15. Input and output voltage swing is a single-ended measurement operating in differential mode.

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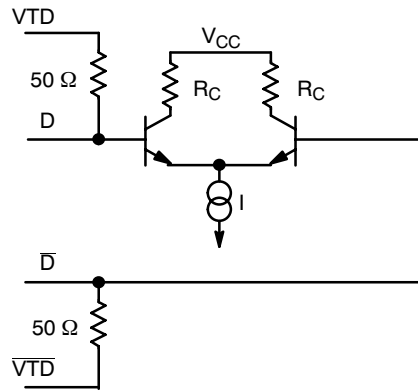


Figure 3. Input Structure

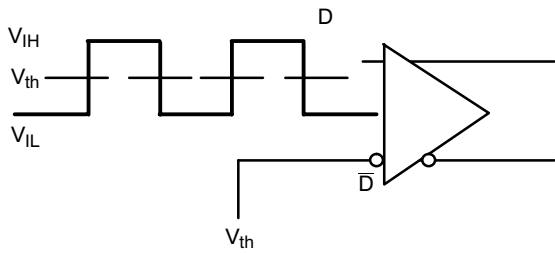


Figure 4. Differential Input Driven Single-Ended

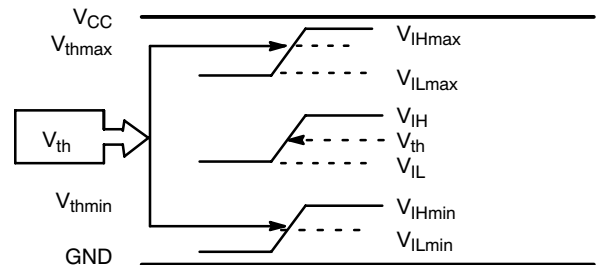


Figure 5.  $V_{th}$  Diagram

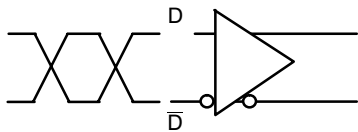


Figure 6. Differential Inputs Driven Differentially

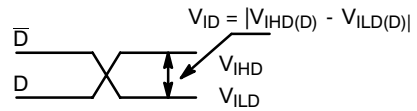


Figure 7. Differential Inputs Driven Differentially

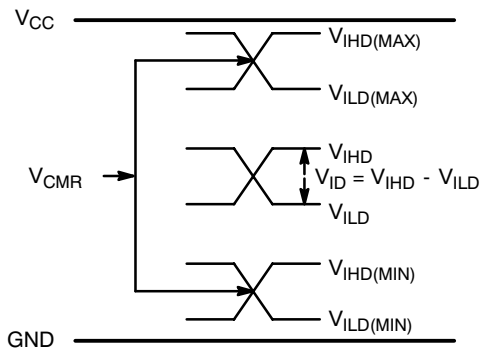


Figure 8.  $V_{CMR}$  Diagram

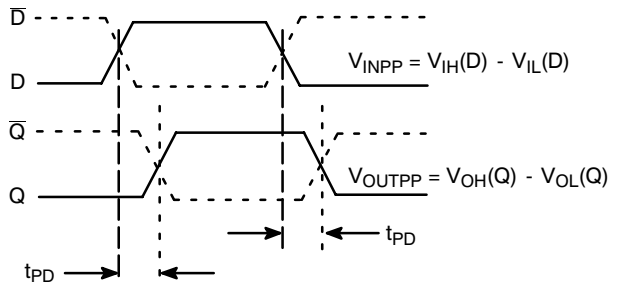


Figure 9. AC Reference Measurement

# NB6L72M

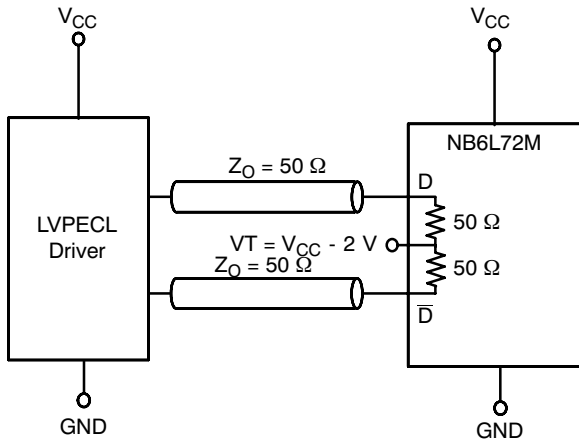


Figure 10. LVPECL Interface

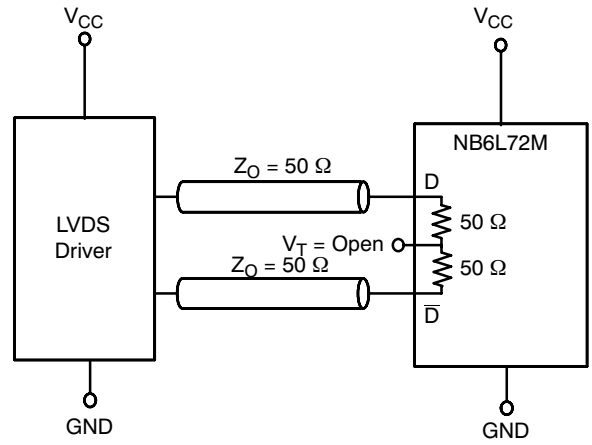


Figure 11. LVDS Interface

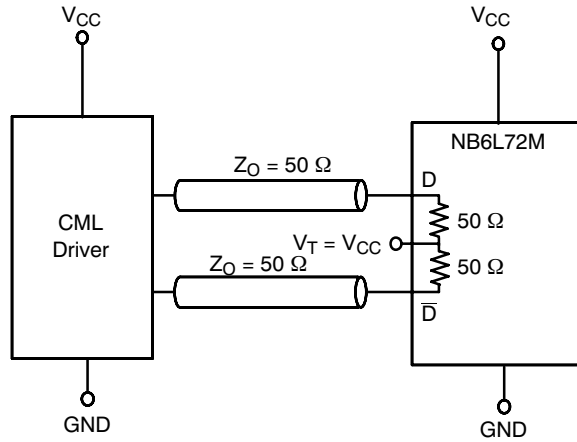


Figure 12. Standard 50 Ω Load CML Interface

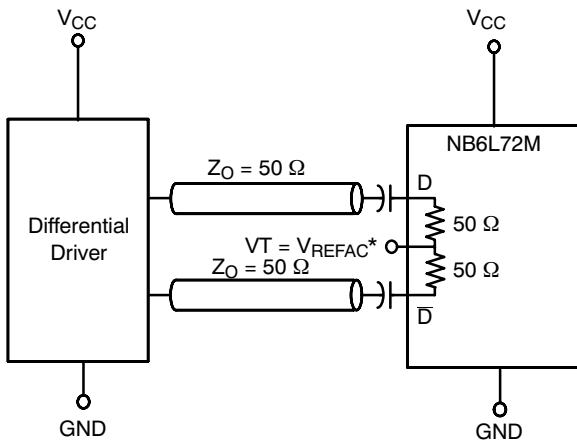


Figure 13. Capacitor-Coupled Differential Interface (VT Connected to  $V_{REFAC}$ )

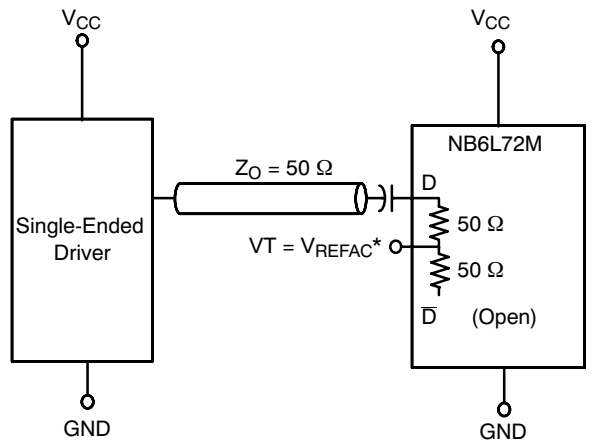


Figure 14. Capacitor-Coupled Single-Ended Interface (VT Connected to  $V_{REFAC}$ )

\* $V_{REFAC}$  bypassed to ground with a 0.01  $\mu$ F capacitor



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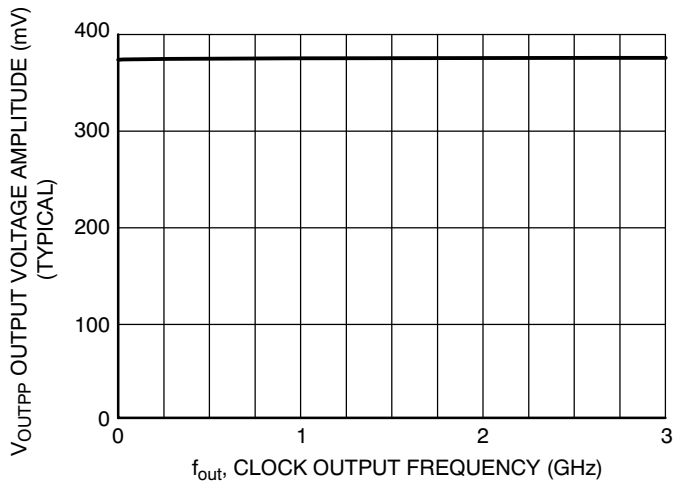


Figure 15. Output Voltage Amplitude ( $V_{OUTPP}$ ) versus Output Frequency at Ambient Temperature (Typical)

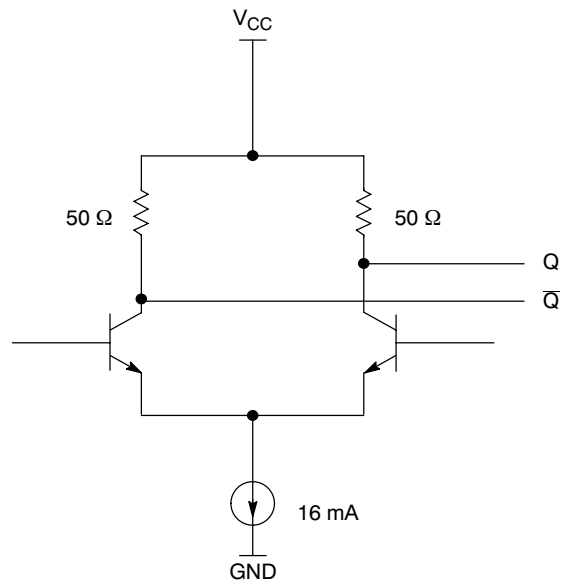


Figure 16. CML Output Structure

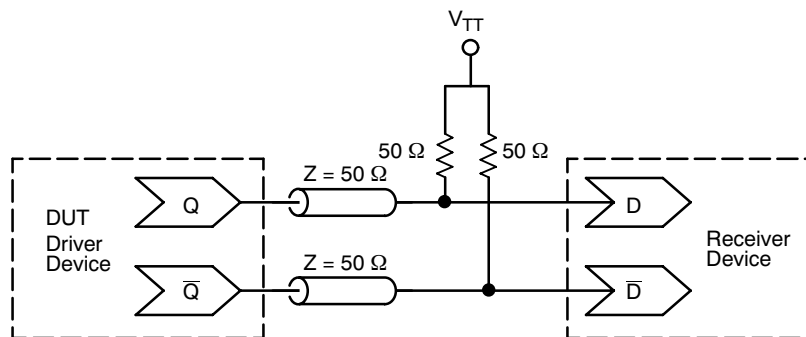


Figure 17. Typical CML Termination for Output Driver and Device Evaluation

## ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
NB6L72MMNG	QFN-16 (Pb-free)	123 Units / Rail
NB6L72MMNR2G	QFN-16 (Pb-free)	3000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

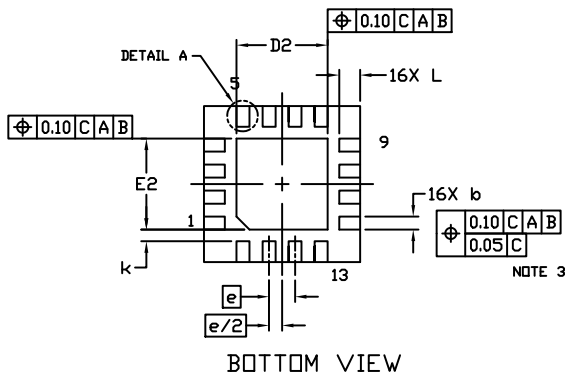
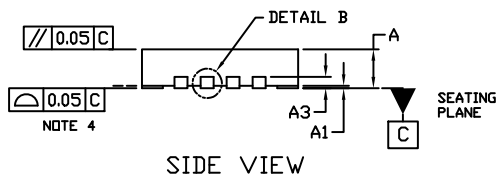
# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SCALE 2:1

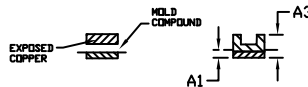
**QFN16 3x3, 0.5P**  
CASE 485G  
ISSUE G

DATE 08 OCT 2021

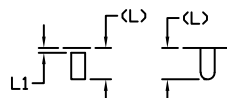


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION *b* APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.



DETAIL B  
ALTERNATE  
CONSTRUCTIONS



DETAIL A  
ALTERNATE TERMINAL  
CONSTRUCTIONS

DIM	MILLIMETERS		
	MIN.	NDM.	MAX.
A	0.80	0.90	1.00
A1	0.00	0.03	0.05
A3	0.20 REF		
<i>b</i>	0.18	0.24	0.30
D	3.00 BSC		
D2	1.65	1.75	1.85
E	3.00 BSC		
E2	1.65	1.75	1.85
<i>e</i>	0.50 BSC		
<i>k</i>	0.18 TYP		
L	0.30	0.40	0.50
L1	0.00	0.08	0.15

**MOUNTING FOOTPRINT**



**GENERIC MARKING DIAGRAM\***



- XXXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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<b>DESCRIPTION:</b>	<b>QFN16 3X3, 0.5P</b>	<b>PAGE 1 OF 1</b>

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